



Material Content Data Sheet



Sales Product Name		BAS 3010S-02LRH E6327		Issued		29. August 2013		
MA#		MA000503734						
Package		PG-TSLP-2-17		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.15		1514	
	noble metal	gold	7440-57-5	0.004	0.59		5874	
	inorganic material	silicon	7440-21-3	0.044	7.17	7.91	71690	79078
leadframe	non noble metal	nickel	7440-02-0	0.138	22.48	22.48	224829	224829
wire	noble metal	gold	7440-57-5	0.012	1.90	1.90	19024	19024
encapsulation	organic material	carbon black	1333-86-4	0.004	0.64		6357	
	plastics	epoxy resin	-	0.053	8.58		85823	
	inorganic material	silicondioxide	60676-86-0	0.334	54.36	63.58	543547	635727
leadfinish	noble metal	gold	7440-57-5	0.010	1.57	1.57	15702	15702
plating	noble metal	silver	7440-22-4	0.016	2.56	2.56	25640	25640
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com